TOSHIBA GTR MODULE SILICON N CHANNEL IGBT

## M G 2 0 0 J 2 Y S 5 0

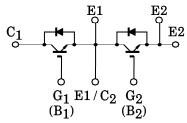
HIGH POWER SWITCHING APPLICATIONS.

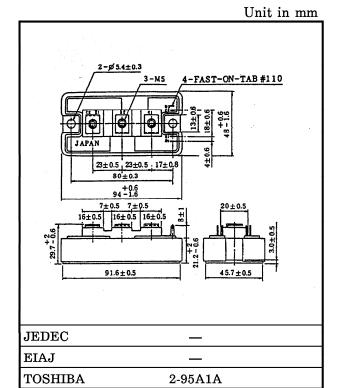
MOTOR CONTROL APPLICATIONS.

- The Electrodes are Isolated from Case.
- High Input Impedance
- Includes a Complete Half Bridge in One Package.
- Enhancement-Mode
- High Speed:  $t_f = 0.30 \mu s$  (Max.) ( $I_C = 200A$ )  $t_{rr} = 0.15 \mu s$  (Max.) (I<sub>F</sub> = 200A)
- Low Saturation Voltage

:  $V_{CE (sat)} = 2.70V (Max.) (I_{C} = 200A)$ 

## **EQUIVALENT CIRCUIT**





## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Collector-Emitter Voltage		$v_{CES}$	600	V	
Gate-Emitter Voltage		$v_{GES}$	±20	V	
Collector Current	DC	$_{ m I_C}$	200	A	
	1ms	$I_{CP}$	400	A	
Forward Current	DC	$I_{\mathbf{F}}$	200	A	
	1ms	$I_{\mathbf{FM}}$	400		
Collector Power Dissipation (Tc=25°C)		PC	900	W	
Junction Temperature		$T_{j}$	150	°C	
Storage Temperature Range		$\mathrm{T_{stg}}$	-40~125	°C	
Isolation Voltage	$v_{Isol}$	2500 (AC 1Min.)	V		
Screw Torque (Terminal/Mounting)		_	3/3	N∙m	

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## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		$I_{ ext{GES}}$	$V_{GE} = \pm 20V, V_{CE} = 0$	_	_	±500	nA
Collector Cut-off Current		$I_{CES}$	$V_{CE} = 600V, V_{GE} = 0$	_		2.0	mA
Gate-Emitter Cut-off Voltage		V <sub>GE (off)</sub>	$I_{C}=20$ mA, $V_{CE}=5$ V	5.0	7.0	8.0	V
Collector-Emitter Saturation Voltage		V <sub>CE</sub> (sat)	$I_{C} = 200A, V_{GE} = 15V$	_	2.10	2.70	V
Input Capaci	tance	$c_{ m ies}$	$V_{CE} = 10V, V_{GE} = 0, f = 1MHz$	-	18000	I	pF
Switching Time	Turn-on Delay Time	t <sub>d (on)</sub>	Inductive Load $V_{CC} = 300V$ $I_{C} = 200A$ $V_{GE} = \pm 15V$ $R_{G} = 4.2\Omega$ (Note 1)	_	0.15	0.30	μs
	Rise Time	$t_{\mathbf{r}}$		_	0.15	0.30	
	Turn-on Time	$t_{on}$		_	0.50	1.00	
	Turn-off Delay Time	<sup>t</sup> d (off)		_	0.20	0.40	
	Fall Time	$t_f$		_	0.15	0.30	
	Turn-off Time	t <sub>off</sub>			0.50	1.00	
Forward Voltage		$ m V_{f F}$	$I_{F} = 200A, V_{GE} = 0$	_	2.30	3.00	V
Reverse Recovery Time		t <sub>rr</sub>	$I_F = 200A$ , $V_{GE} = -10V$ di / dt = 200A / $\mu$ s		0.08	0.15	μs
Thermal Resistance		R <sub>th (j-c)</sub>	Transistor Stage	_	_	0.14	վ°C/W
			Diode Stage	_	_	0.35	

Note 1 Switching Time Test Circuit & Timing Chart

